Kulicke & Soffa Introduces Comprehensive Solution For Fine Aluminum (Wedge-to-Wedge) Wire Bonding

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment, today announced the introduction of a comprehensive solution dedicated for Fine Aluminum (Wedge-to-Wedge) Wire Bonding - with the new launched VitaCap™ Series of Capillaries and IConnPS *PLUS*™ Ball Bonder.

VitaCap™ is made from K&S' leading ITA™ ceramics material, engineered for high quality Aluminum wedge bond and tail bond formation on any wire direction. Its unique features fit well with IConnPS *PLUS*™ Ball Bonder's special wedge-to-wedge feature. Together, they deliver an innovative wire bonding platform for applications that uses fine Aluminum wire diameters (0.6-2.0 mil), supporting the Automotive, RF, Medical, LED and consumer segments.

The key advantages of this comprehensive solution are:

- Flexibility of using the Ball Bonder for either Aluminum or Gold wire
- Improved productivity resulting in lower cost of ownership over traditional wedge bonder
- Applicable for low loop application
- Capable to bond at low or room temperature
- Eliminate the use of forming gas to reduce cost

Chan Pin Chong, Kulicke & Soffa's Vice President of the Wedge Bonders, Capillaries and Blades Business Lines, said, "Customers will benefit from the comprehensive solution of our bonder system together with the application of VitaCap™, achieving higher throughput and process stability, while also lowering the cost of ownership."

Nelson Wong, Kulicke & Soffa's Vice President of the Ball Bonder Business Line, remarked, "Kulicke & Soffa continues to focus on research and development to bring solutions to customers with unparalleled performance. The VitaCap™ coupled with our K&S Ball bonder provides one of the most innovative solutions on extending Fine Aluminum wire application."

The VitaCap™ will debut at the SEMICON China show at the Shanghai New International Expo Centre, Hall N5, Booth #5331, from March 15-17, 2016. Please contact your local sales and services representative for more information on K&S' comprehensive solutions.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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